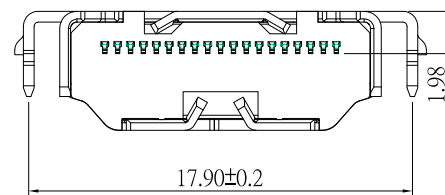
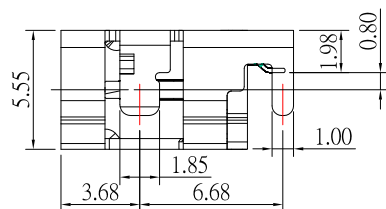
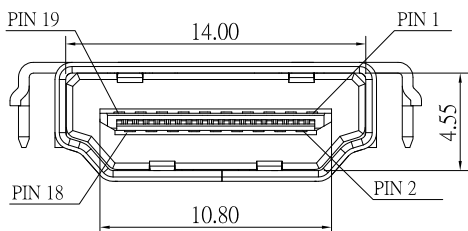
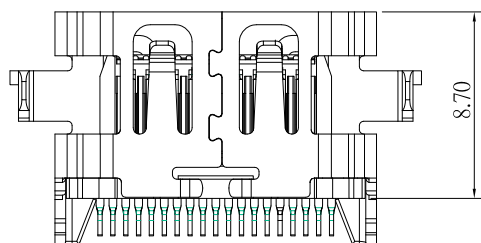


RECOMMENDED P.C.B. LAYOUT



NOTE:

- 1.MATERIAL:
 - 1.1 HOUSING: LCP
 - 1.2 CONTACT: BRASS
 - 1.3 SHEEL: SPCC
- 2.PLATING :
 - 2.1 CONTACT: PLATED GOLD IN MATING AREA ;
TIN PLATED ON SOLDER BALLS ;
NICKEL UNDER PLATED OVERALL
 - 2.2 SHELL: NICKEL UNDER PLATED SURFACE LAYER
OR GOLD UNDER PLATED SURFACE LAYER
- 3.MECHANICAL:
 - 3.1 INSERTION FORCE: 4.5 Kgf MAX
 - 3.2 WITHDRAWAL FORCE: 1.0 ~ 4.0 Kgf
- 4.ELECTRICAL:
 - 4.1 CONTACT RESISTANCE: 30 mΩ Max
 - 4.2 INSULATION RESISTANCE: 100MΩ Min
 - 4.3 DIELECTRIC WITHSTANDING VOLTAGE: 500V AC / minute



CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED :
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3°

3RD. ANGEL'S



UNITS MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	11/17/22			
CHECKED BY:	DATE	FINISH	MODLE	HDMI2.1 AF MID-MOUNT CL-0.8mm
Jacky Chen	11/17/22			
APPROVED BY:	DATE	SCALE	DWG NO.	HD2-19P-SND231-S165
Tony Kao	11/17/22	1 : 1	PART NO.	HD2-19P-SND231-S165
		SHEET NO.	1 of 1	
				SIZE A4
				VER R2

2	新增PCB LAYOUT尺寸	Jack	111722
1	更新料號	Jack	111122
ITEM NO.	DESCRIPTION	DRAWN	DATE